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film which is to be removed at a time of lamination of the photosensitive film on a substrate.

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20. A photosensitive film according to Claim 19, wherein the photosensitive resin layer has a further film, on a side thereof opposite to the side upon which the film having fish eyes of a diameter of at least 80 $\mu$ m in a number not exceeding 5 per square meter is stuck.

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21. A photosensitive film according to Claim 20, wherein adhesive strength between the photosensitive resin layer and the further film on the opposite side is greater than adhesive strength between the photosensitive resin layer and the film.

22. A photosensitive film according to Claim 20, wherein the further film has a film thickness of 12 to 25 $\mu$ m.

23. A photosensitive film according to Claim 19, wherein the photosensitive resin layer is made from a resin composition comprising:

(a) a binder polymer formed by copolymerizing acrylic acid or methacrylic acid and alkyl esters thereof as constituent monomers,

(b) a monomer having at least one polymerizable ethylenically unsaturated group in the molecule thereof, and

(c) a photopolymerization initiator.

*C6  
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cont*

24. A photosensitive film according to Claim 23, wherein the binder polymer (a) contains a carboxyl group-containing monomer in an amount of 12 to 40% by weight based on the total amount of the monomers, has a weight-average molecular weight of 20,000 to 300,000, and is used in an amount of 40 to 80 parts by weight, the monomer (b) is used in an amount of 20 to 60 parts by weight and the photopolymerization initiator (c) is used in an amount of 0.1 to 20 parts by weight, based on 100 parts by weight of the total amounts of (a) and (b).

25. A photosensitive film according to Claim 23, wherein the binder polymer (a) contains methacrylic acid as a constituent monomer.

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26. A photosensitive film according to Claim 23, wherein the monomer (b) is bisphenol A polyoxyalkylene diacrylate or contains bisphenol A polyoxyalkylene diacrylate as a component.

27. A photosensitive film according to Claim 23, wherein the photopolymerization initiator (c) contains 2,4,5-triarylimidazole dimer.

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28. A photosensitive film according to Claim 19, wherein the film is a polypropylene film.

29. A photosensitive film according to Claim 19, wherein the photosensitive film is a film for use in a metal etching process.

B<sup>1</sup>  
B<sub>2</sub>  
Cont

30. A photosensitive film according to Claim 19, wherein the photosensitive resin layer has a viscosity of 15 to 50 MPa·s at 30°C.

31. A photosensitive film according to Claim 19, wherein the film has a thickness of 5 to 50μm.

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32. A photosensitive film according to Claim 19, wherein the film is a film removed at a time of lamination of the photosensitive film on a substrate.

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33. A process for laminating a photosensitive film on a substrate, which comprises laminating the photosensitive film of Claim 19 on a substrate, while removing the film so as to make the photosensitive resin layer adhere to the substrate.

34. A photosensitive resin layer laminated substrate obtained by the process of Claim 33.

35. A process for curing a photosensitive resin layer, which comprises exposing the photosensitive resin layer laminated substrate of Claim 34 to light.--

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